

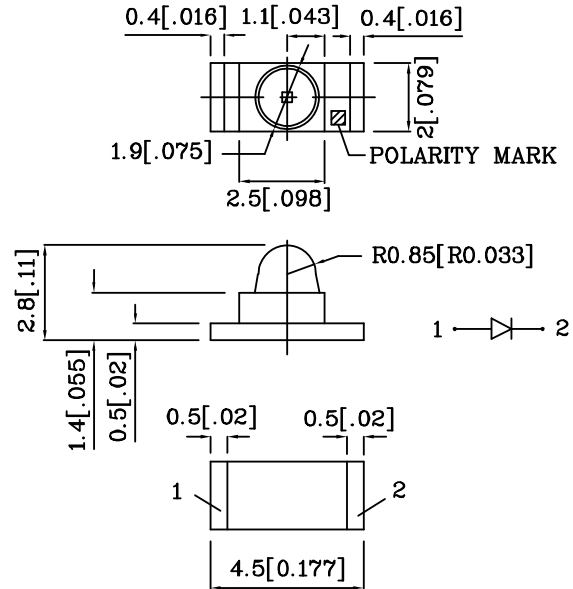
### Features

- 4.5x2mm SMT LED, 0.5mm THICKNESS
- LOW POWER CONSUMPTION.
- IDEAL FOR BACK LIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 1000PCS/REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.



### Notes:

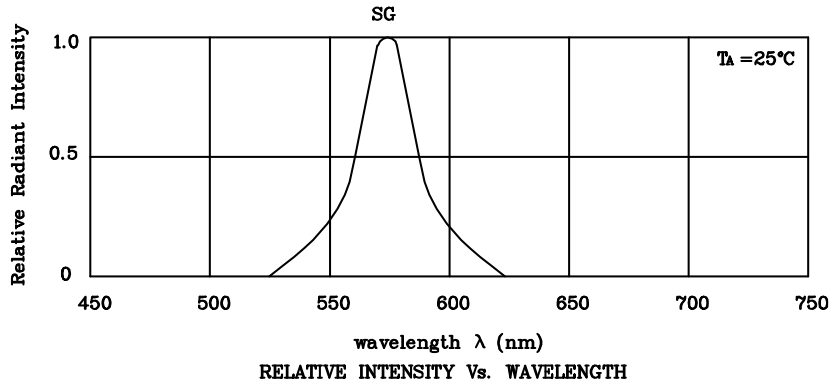
1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.2(0.008)$ " unless otherwise noted.
3. Specifications are subject to change without notice.



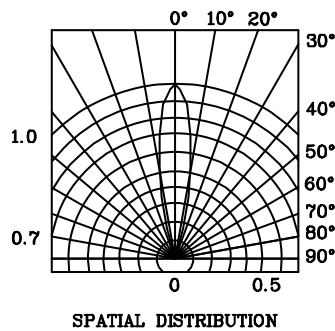
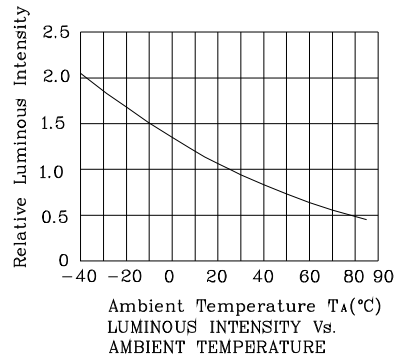
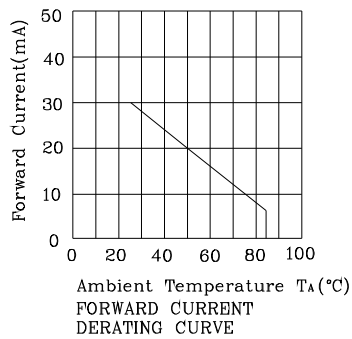
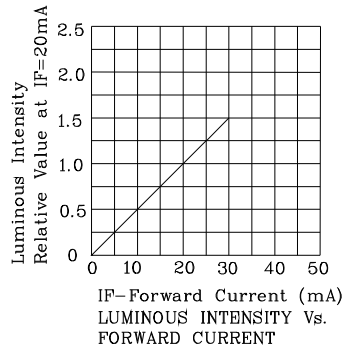
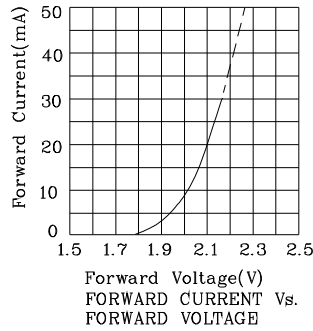
Absolute Maximum Ratings (TA=25°C)		SG (InGaAlP)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	150	mA
Power Dissipation	P <sub>T</sub>	75	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	

Operating Characteristics (TA=25°C)		SG (InGaAlP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	V <sub>F</sub>	2.1	V
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	V <sub>F</sub>	2.5	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	I <sub>R</sub>	10	uA
Wavelength Of Peak Emission (Typ.) (I <sub>F</sub> =20mA)	λ <sub>P</sub>	574	nm
Wavelength Of Dominant Emission (Typ.) (I <sub>F</sub> =20mA)	λ <sub>D</sub>	568	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	Δλ	26	nm
Capacitance (V <sub>F</sub> =0V, f=1MHz)	C	20	pF

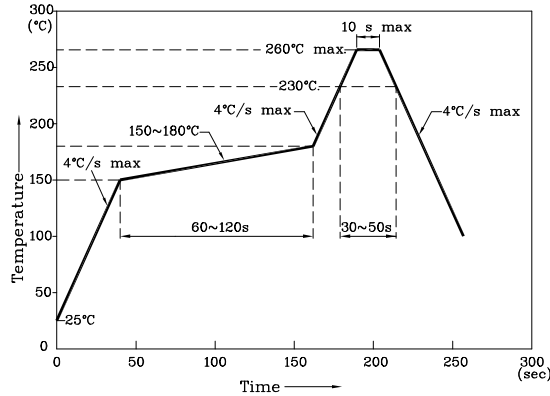
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I <sub>F</sub> =20mA) mcd		Wavelength nm λ <sub>P</sub>	Viewing Angle 2θ 1/2
				min.	typ.		
XZSG77W	Green	InGaAlP	Water Clear	110	397	574	20°
Published Date : JAN 21, 2008      Drawing No : XDSA1760      V5      Checked : B.L.LIU      P.1/4							



❖ SG



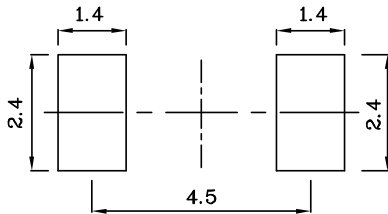
Reflow Soldering Profile For Lead-free SMT Process.



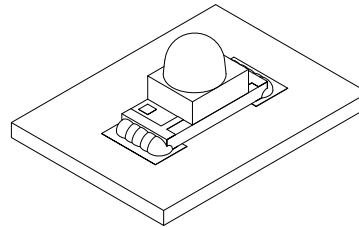
NOTES:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

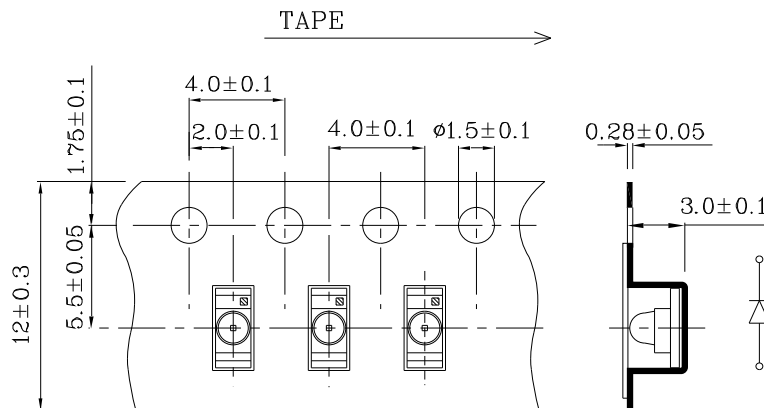
❖ Recommended Soldering Pattern  
(Units : mm; Tolerance: ± 0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

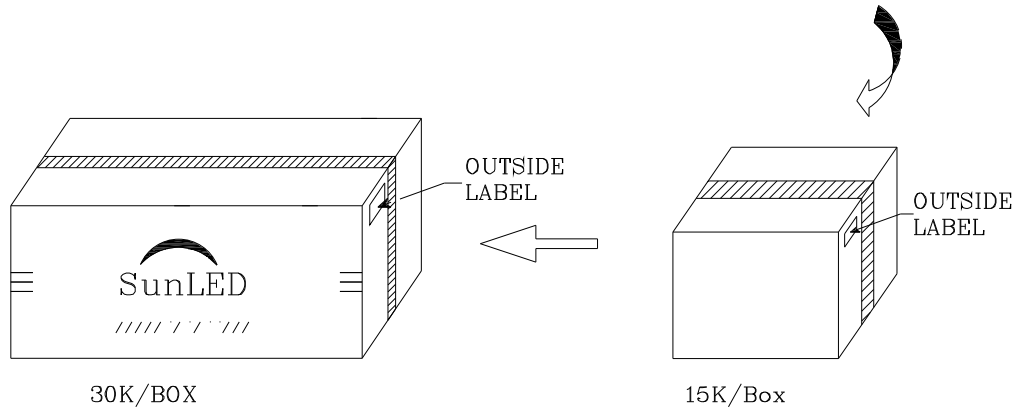
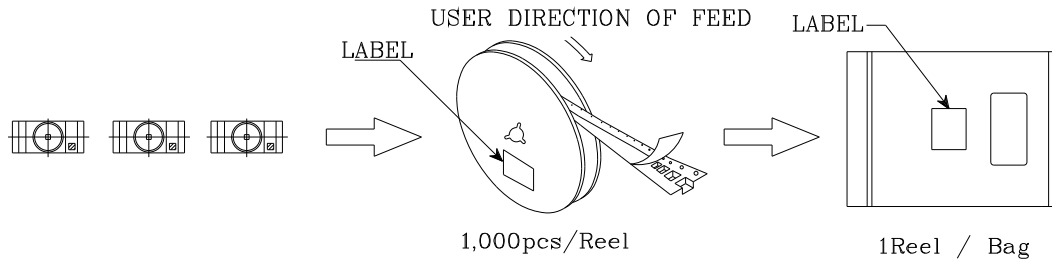
If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux or wavelength), the typical accuracy of the sorting process is as follows:


1. Wavelength: +/-1nm
2. Luminous Intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

**PACKING & LABEL SPECIFICATIONS**

**XZSG77W**



P/NO : XZxxx77x	
QTY : 1,000 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 XXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	